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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

FAIRCHILD SEMICONDUCTOR®

January 2011

Single-Channel: 6N137, HCPL2601, HCPL2611 Dual-Channel: HCPL2630, HCPL2631 High Speed 10MBit/s Logic Gate Optocouplers

Features

- Very high speed – 10 MBit/s
- Superior CMR – 10 kV/µs
- Double working voltage-480V
- Fan-out of 8 over -40°C to +85°C
- Logic gate output
- Strobable output
- Wired OR-open collector
- U.L. recognized (File # E90700)

Applications

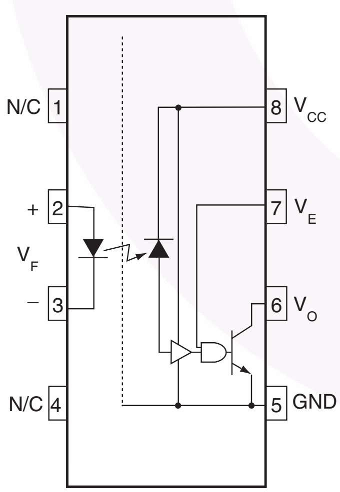
- Ground loop elimination
- LSTTL to TTL, LSTTL or 5-volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer-peripheral interface

Description

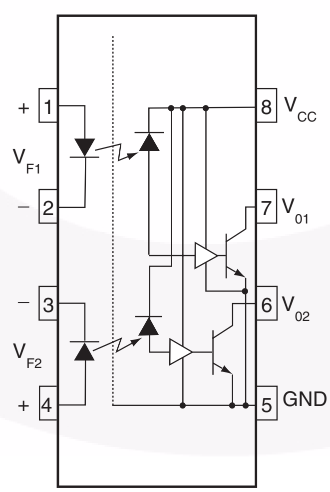
The 6N137, HCPL2601, HCPL2611 single-channel and HCPL2630, HCPL2631 dual-channel optocouplers consist of a 850 nm AlGaAS LED, optically coupled to a very high speed integrated photo-detector logic gate with a strobable output. This output features an open collector, thereby permitting wired OR outputs. The coupled parameters are guaranteed over the temperature range of -40°C to +85°C. A maximum input signal of 5mA will provide a minimum output sink current of 13mA (fan out of 8).

An internal noise shield provides superior common mode rejection of typically 10kV/µs. The HCPL2601 and HCPL2631 has a minimum CMR of 5kV/µs. The HCPL2611 has a minimum CMR of 10kV/µs.

Schematics



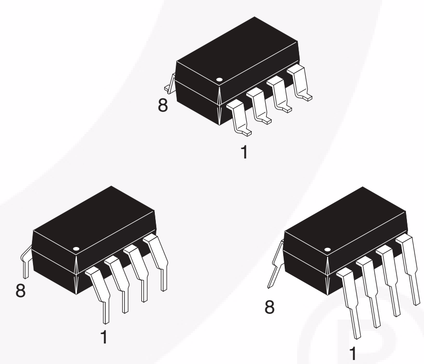
6N137
HCPL2601
HCPL2611



HCPL2630
HCPL2631

A 0.1µF bypass capacitor must be connected between pins 8 and 5(1).

Package Outlines



Truth Table (Positive Logic)

Input	Enable	Output
H	H	L
L	H	H
H	L	H
L	L	H
H	NC	L
L	NC	H

Absolute Maximum Ratings (T_A = 25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Value	Units
T_{STG}	Storage Temperature		-55 to +125	°C
T_{OPR}	Operating Temperature		-40 to +85	°C
T_{SOL}	Lead Solder Temperature (for wave soldering only)*		260 for 10 sec	°C
EMITTER				
I_F	DC/Average Forward Input Current	Single Channel	50	mA
		Dual Channel (Each Channel)	30	
V_E	Enable Input Voltage Not to Exceed V_{CC} by more than 500mV	Single Channel	5.5	V
V_R	Reverse Input Voltage	Each Channel	5.0	V
P_I	Power Dissipation	Single Channel	100	mW
		Dual Channel (Each Channel)	45	
DETECTOR				
V_{CC} (1 minute max)	Supply Voltage		7.0	V
I_O	Output Current	Single Channel	50	mA
		Dual Channel (Each Channel)	50	
V_O	Output Voltage	Each Channel	7.0	V
P_O	Collector Output Power Dissipation	Single Channel	85	mW
		Dual Channel (Each Channel)	60	

*For peak soldering reflow, please refer to the Reflow Profile on page 11.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Units
I_{FL}	Input Current, Low Level	0	250	µA
I_{FH}	Input Current, High Level	*6.3	15	mA
V_{CC}	Supply Voltage, Output	4.5	5.5	V
V_{EL}	Enable Voltage, Low Level	0	0.8	V
V_{EH}	Enable Voltage, High Level	2.0	V_{CC}	V
T_A	Low Level Supply Current	-40	+85	°C
N	Fan Out (TTL load)		8	

*6.3mA is a guard banded value which allows for at least 20% CTR degradation. Initial input current threshold value is 5.0mA or less.

Electrical Characteristics (T_A = 0 to 70°C unless otherwise specified)

Individual Component Characteristics

Symbol	Parameter	Test Conditions		Min.	Typ.*	Max.	Unit
EMITTER							
V_F	Input Forward Voltage	I_F = 10mA				1.8	V
			T_A = 25°C		1.4	1.75	
B_{VR}	Input Reverse Breakdown Voltage	I_R = 10µA		5.0			V
C_{IN}	Input Capacitance	V_F = 0, f = 1MHz			60		pF
$\Delta V_F / \Delta T_A$	Input Diode Temperature Coefficient	I_F = 10mA			-1.4		mV/°C
DETECTOR							
I_{CCH}	High Level Supply Current	V_{CC} = 5.5V, I_F = 0mA, V_E = 0.5V	Single Channel		7	10	mA
			Dual Channel		10	15	
I_{CCL}	Low Level Supply Current	Single Channel	V_{CC} = 5.5V, I_F = 10mA		9	13	mA
		Dual Channel	V_E = 0.5V		14	21	
I_{EL}	Low Level Enable Current	V_{CC} = 5.5V, V_E = 0.5V			-0.8	-1.6	mA
I_{EH}	High Level Enable Current	V_{CC} = 5.5V, V_E = 2.0V			-0.6	-1.6	mA
V_{EH}	High Level Enable Voltage	V_{CC} = 5.5V, I_F = 10mA		2.0			V
V_{EL}	Low Level Enable Voltage	V_{CC} = 5.5V, I_F = 10mA[3]				0.8	V

Switching Characteristics (T_A = -40°C to +85°C, V_{CC} = 5V, I_F = 7.5mA unless otherwise specified)

Symbol	AC Characteristics	Test Conditions		Min.	Typ.*	Max.	Unit
T_{PLH}	Propagation Delay Time to Output HIGH Level	R_L = 350Ω, C_L = 15pF[4] (Fig. 12)	T_A = 25°C	20	45	75	ns
						100	
T_{PHL}	Propagation Delay Time to Output LOW Level	T_A = 25°C[5]		25	45	75	ns
		R_L = 350Ω, C_L = 15pF (Fig. 12)				100	
$\lvert T_{PHL}-T_{PLH}\rvert$	Pulse Width Distortion	(R_L = 350Ω, C_L = 15pF (Fig. 12)			3	35	ns
t_r	Output Rise Time (10–90%)	R_L = 350Ω, C_L = 15pF[6] (Fig. 12)			50		ns
t_f	Output Rise Time (90–10%)	R_L = 350Ω, C_L = 15pF[7] (Fig. 12)			12		ns
t_{ELH}	Enable Propagation Delay Time to Output HIGH Level	I_F = 7.5mA, V_{EH} = 3.5V, R_L = 350Ω, C_L = 15pF[8] (Fig. 13)			20		ns
t_{EHL}	Enable Propagation Delay Time to Output LOW Level	I_F = 7.5mA, V_{EH} = 3.5V, R_L = 350Ω, C_L = 15pF[9] (Fig. 13)			20		ns
$\lvert CM_H\rvert$	Common Mode Transient Immunity (at Output HIGH Level)	T_A = 25°C, $\lvert V_{CM}\rvert$ = 50V (Peak), I_F = 0mA, V_{OH} (Min.) = 2.0V, R_L = 350Ω[10] (Fig. 14)	6N137, HCPL2630		10,000		V/µs
			HCPL2601, HCPL2631	5000	10,000		
		$\lvert V_{CM}\rvert$ = 400V	HCPL2611	10,000	15,000		V/µs
$\lvert CM_L\rvert$	Common Mode Transient Immunity (at Output LOW Level)	R_L = 350Ω, I_F = 7.5mA, V_{OL} (Max.) = 0.8V, T_A = 25°C[11] (Fig. 14)	6N137, HCPL2630		10,000		
			HCPL2601, HCPL2631	5000	10,000		
		$\lvert V_{CM}\rvert$ = 400V	HCPL2611	10,000	15,000		

Electrical Characteristics (Continued)

Transfer Characteristics (T_A = -40 to +85°C unless otherwise specified)

Symbol	DC Characteristics	Test Conditions	Min.	Typ.*	Max.	Unit
I_{OH}	HIGH Level Output Current	V_{CC} = 5.5V, V_O = 5.5V, I_F = 250µA, V_E = 2.0V(2)			100	µA
V_{OL}	LOW Level Output Current	V_{CC} = 5.5V, I_F = 5mA, V_E = 2.0V, I_{CL} = 13mA(2)		.35	0.6	V
I_{FT}	Input Threshold Current	V_{CC} = 5.5V, V_O = 0.6V, V_E = 2.0V, I_{OL} = 13mA		3	5	mA

Isolation Characteristics (T_A = -40°C to +85°C unless otherwise specified.)

Symbol	Characteristics	Test Conditions	Min.	Typ.*	Max.	Unit
I_{I-O}	Input-Output Insulation Leakage Current	Relative humidity = 45%, T_A = 25°C, t = 5s, V_{I-O} = 3000 VDC(12)			1.0*	µA
V_{ISO}	Withstand Insulation Test Voltage	RH < 50%, T_A = 25°C, I_{I-O} ≤ 2µA, t = 1 min.(12)	2500			V_{RMS}
R_{I-O}	Resistance (Input to Output)	V_{I-O} = 500V(12)		10^{12}		Ω
C_{I-O}	Capacitance (Input to Output)	f = 1MHz(12)		0.6		pF

*All Typicals at V_{CC} = 5V, T_A = 25°C

Notes:

1. The V_{CC} supply to each optoisolator must be bypassed by a 0.1µF capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package V_{CC} and GND pins of each device.
2. Each channel.
3. Enable Input – No pull up resistor required as the device has an internal pull up resistor.
4. t_{PLH} – Propagation delay is measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
5. t_{PHL} – Propagation delay is measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
6. t_r – Rise time is measured from the 90% to the 10% levels on the LOW to HIGH transition of the output pulse.
7. t_f – Fall time is measured from the 10% to the 90% levels on the HIGH to LOW transition of the output pulse.
8. t_{ELH} – Enable input propagation delay is measured from the 1.5V level on the HIGH to LOW transition of the input voltage pulse to the 1.5V level on the LOW to HIGH transition of the output voltage pulse.
9. t_{EHL} – Enable input propagation delay is measured from the 1.5V level on the LOW to HIGH transition of the input voltage pulse to the 1.5V level on the HIGH to LOW transition of the output voltage pulse.
10. CM_H – The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., V_{OUT} > 2.0V). Measured in volts per microsecond (V/µs).
11. CM_L – The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e., V_{OUT} < 0.8V). Measured in volts per microsecond (V/µs).
12. Device considered a two-terminal device: Pins 1, 2, 3 and 4 shorted together, and Pins 5, 6, 7 and 8 shorted together.

Typical Performance Curves

Fig.1 Low Level Output Voltage vs. Ambient Temperature

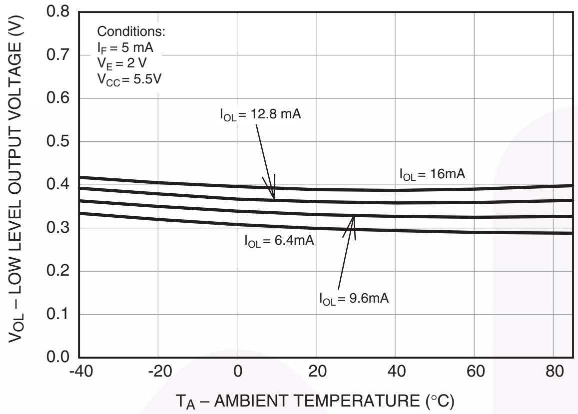


Fig. 2 Input Diode Forward Voltage vs. Forward Current

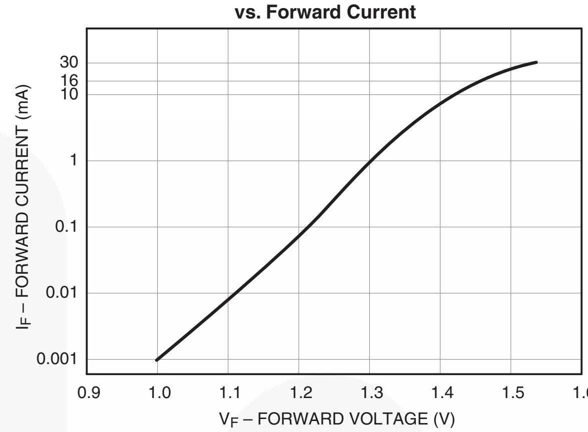


Fig.3 Switching Time vs. Forward Current

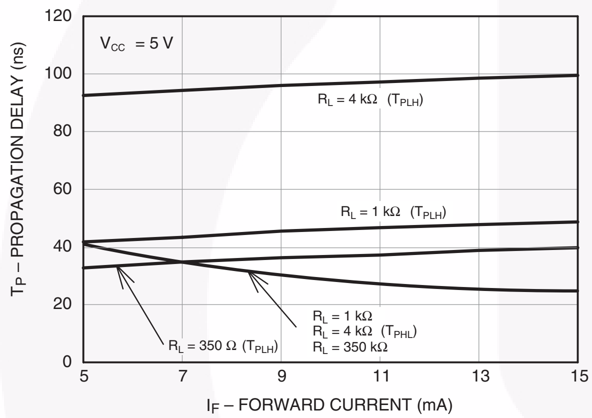


Fig. 4 Low Level Output Current vs. Ambient Temperature

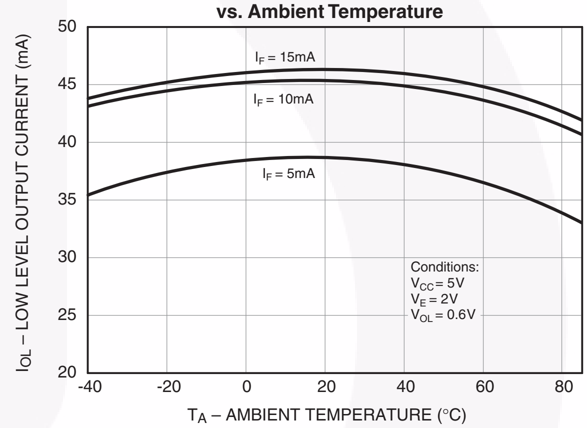


Fig. 5 Input Threshold Current vs. Ambient Temperature

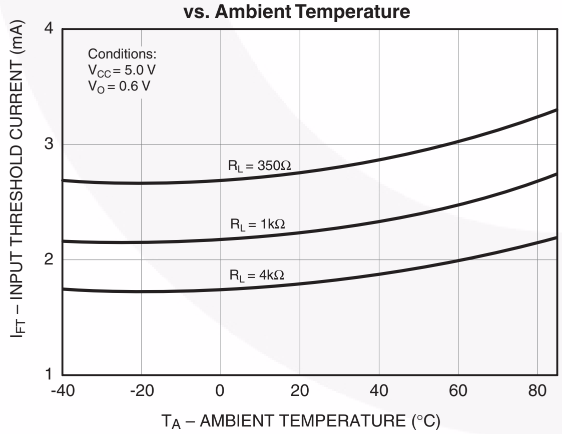
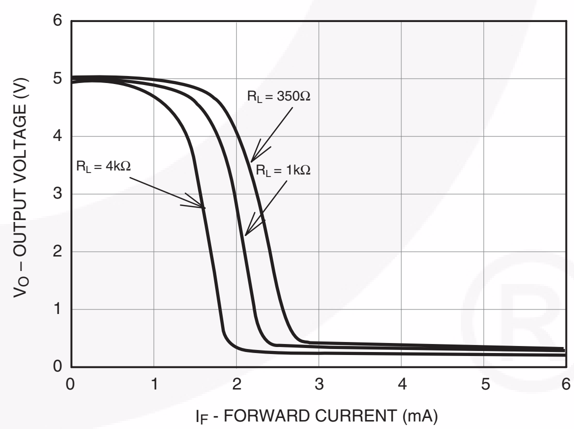


Fig. 6 Output Voltage vs. Input Forward Current



Typical Performance Curves (Continued)

Fig. 7 Pulse Width Distortion vs. Temperature

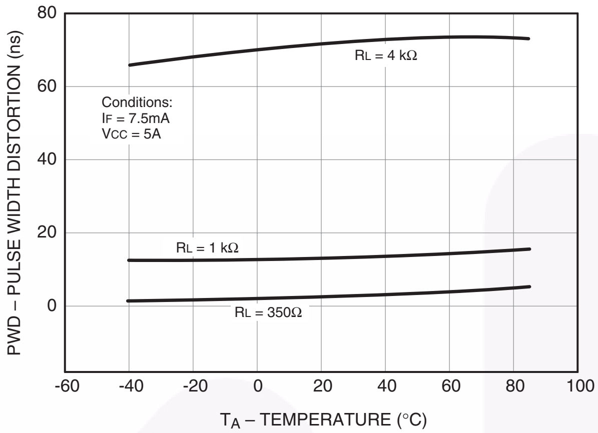


Fig. 8 Rise and Fall Time vs. Temperature

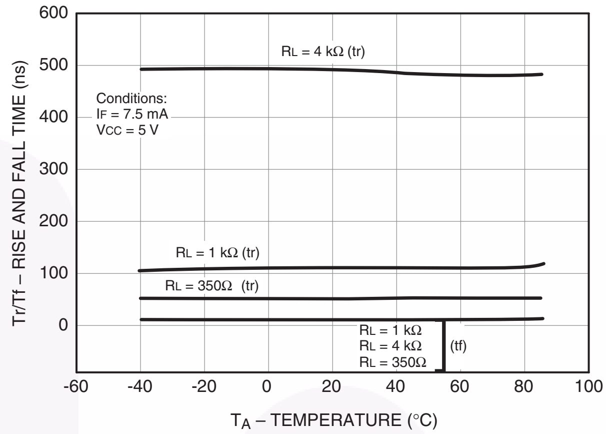


Fig. 9 Enable Propagation Delay vs. Temperature

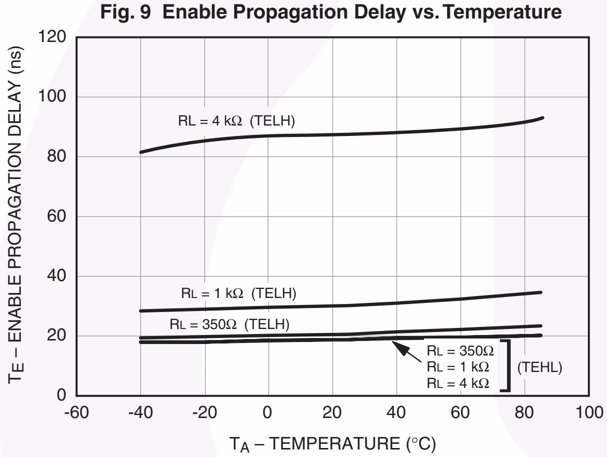


Fig. 10 Switching Time vs. Temperature

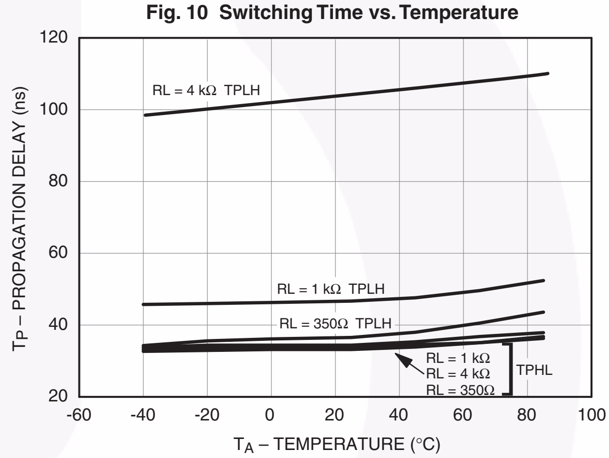
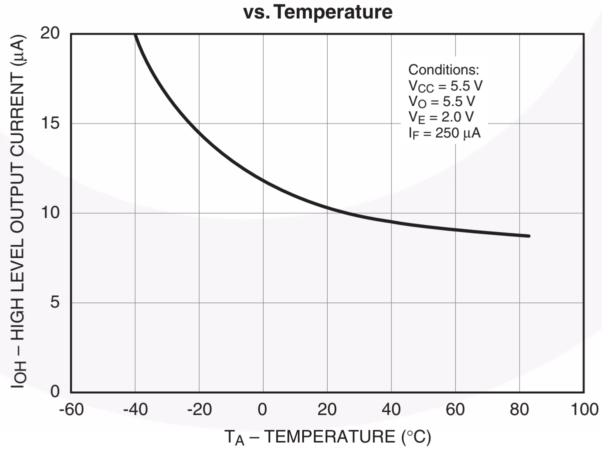


Fig. 11 High Level Output Current vs. Temperature



Test Circuits

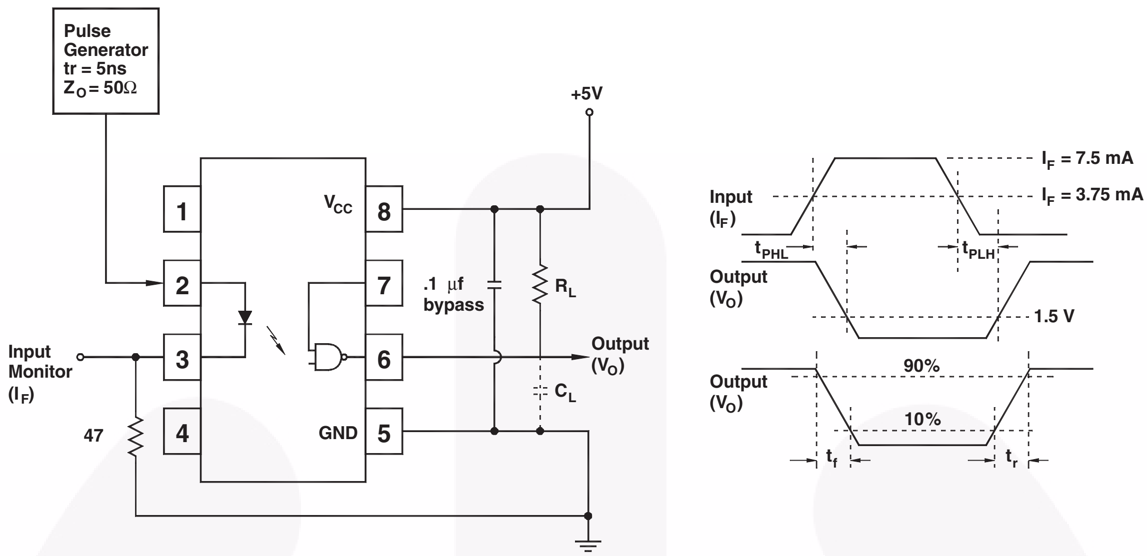


Fig. 12 Test Circuit and Waveforms for t_{PLH}, t_{PHL}, t_r and t_f

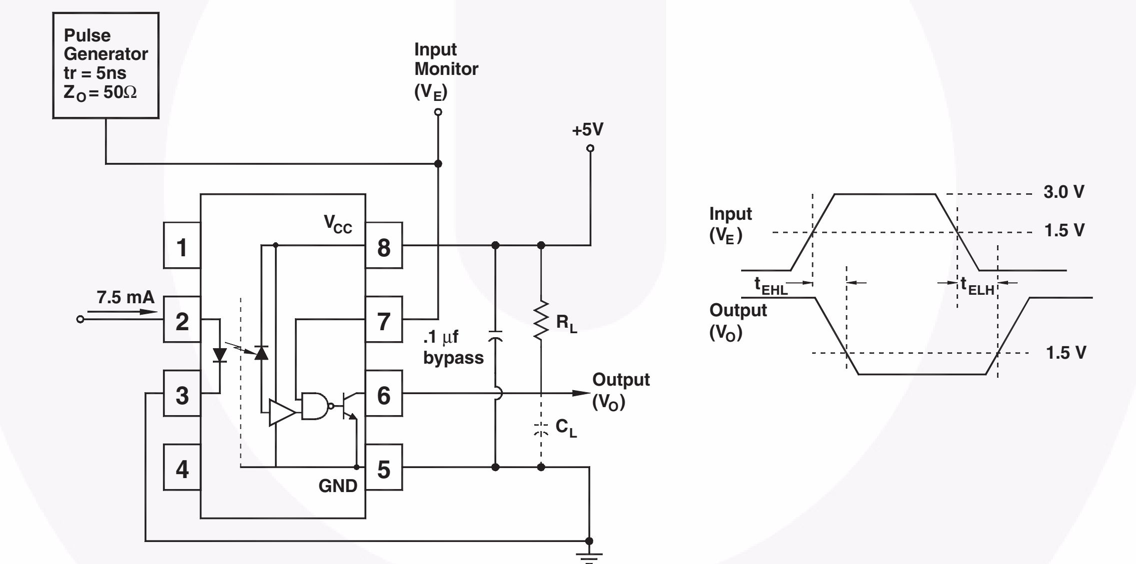


Fig. 13 Test Circuit t_{EHL} and t_{ELH}

Test Circuits (Continued)

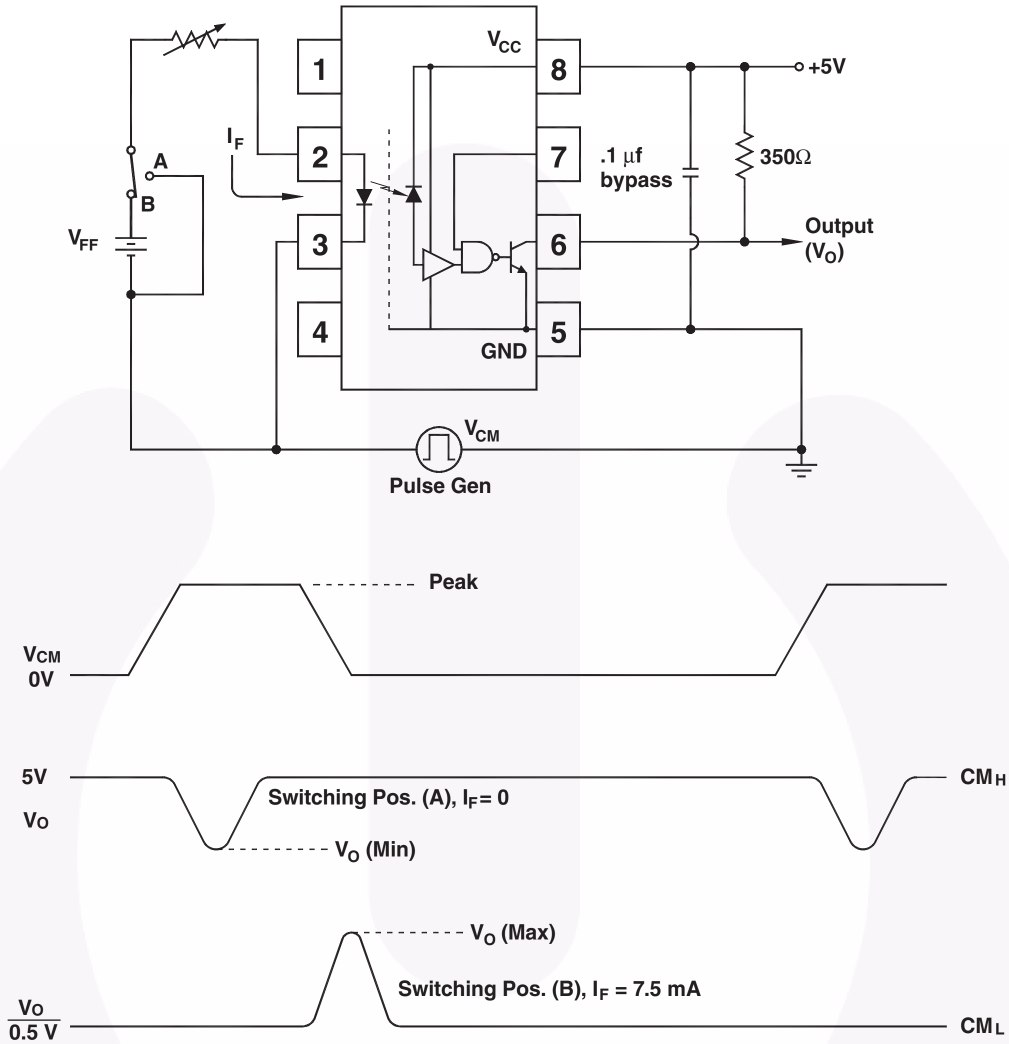
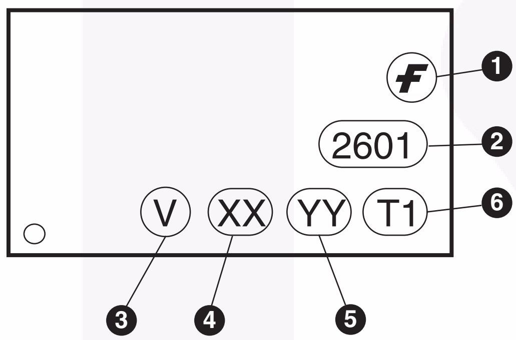


Fig. 14 Test Circuit Common Mode Transient Immunity

Ordering Information

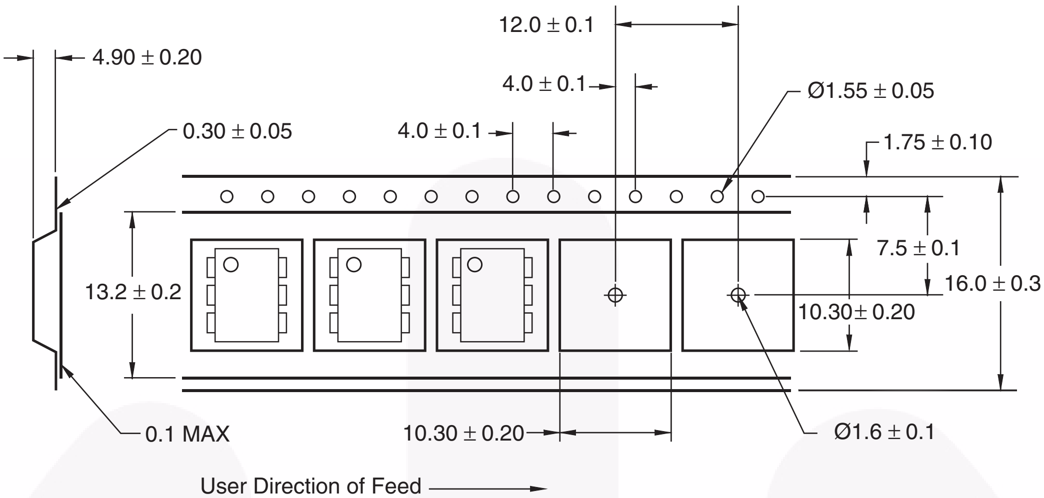
Option	Example Part Number	Description
S	6N137S	Surface Mount Lead Bend
SD	6N137SD	Surface Mount; Tape and Reel
W	6N137W	0.4" Lead Spacing
V	6N137V	VDE0884
WV	6N137WV	VDE0884; 0.4” Lead Spacing
SV	6N137SV	VDE0884; Surface Mount
SDV	6N137SDV	VDE0884; Surface Mount; Tape and Reel

Marking Information

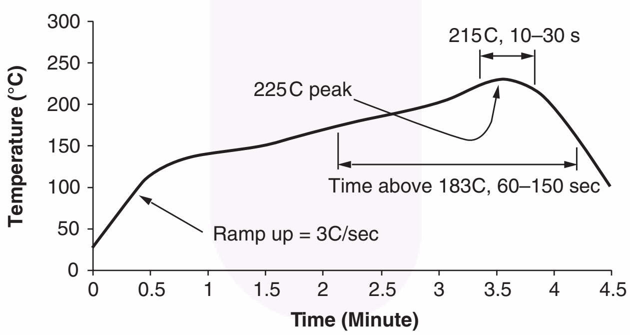


Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., ‘03’
5	Two digit work week ranging from ‘01’ to ‘53’
6	Assembly package code

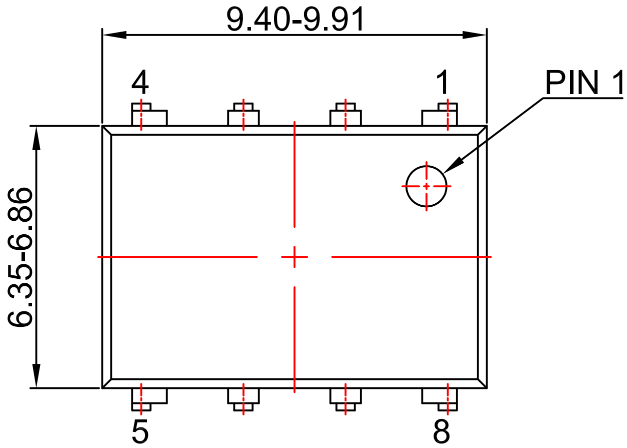
Tape Specifications

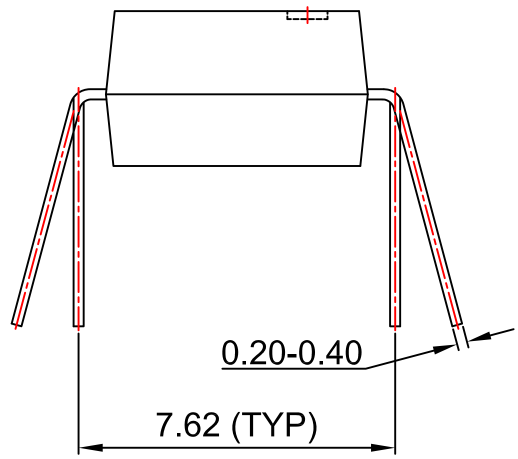


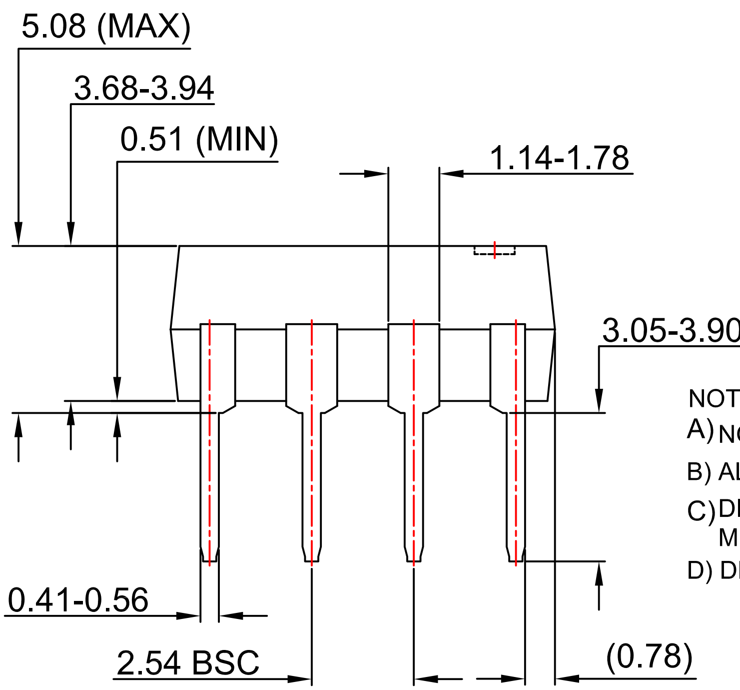
Reflow Profile



- Peak reflow temperature: 225C (package surface temperature)
- Time of temperature higher than 183C for 60–150 seconds
- One time soldering reflow is recommended







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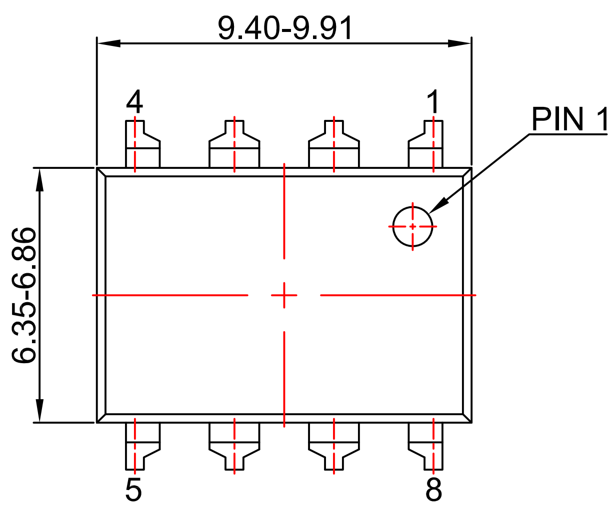
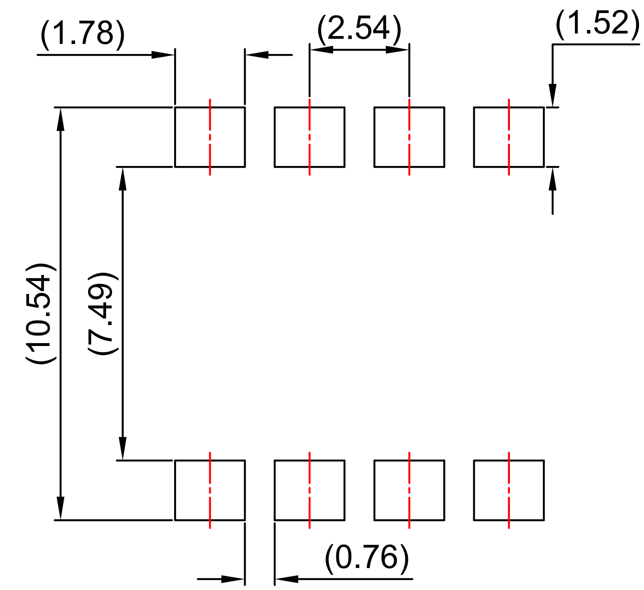
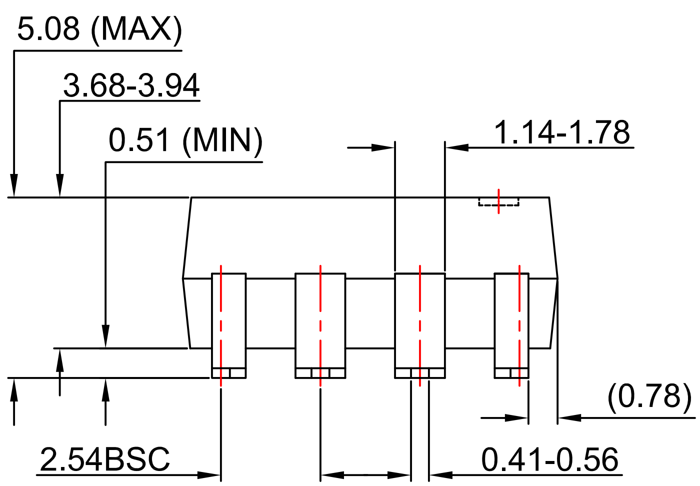
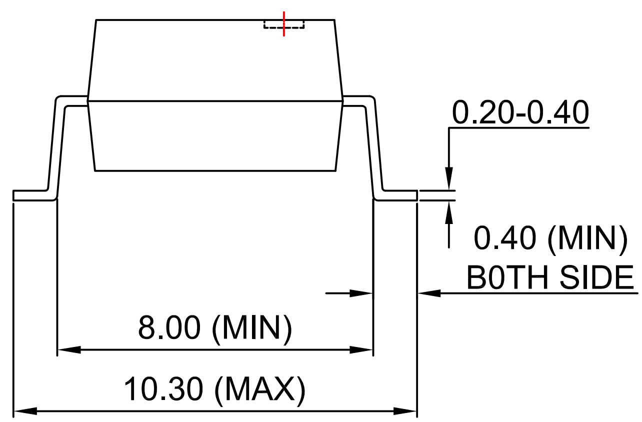




LAND PATTERN RECOMMENDATION





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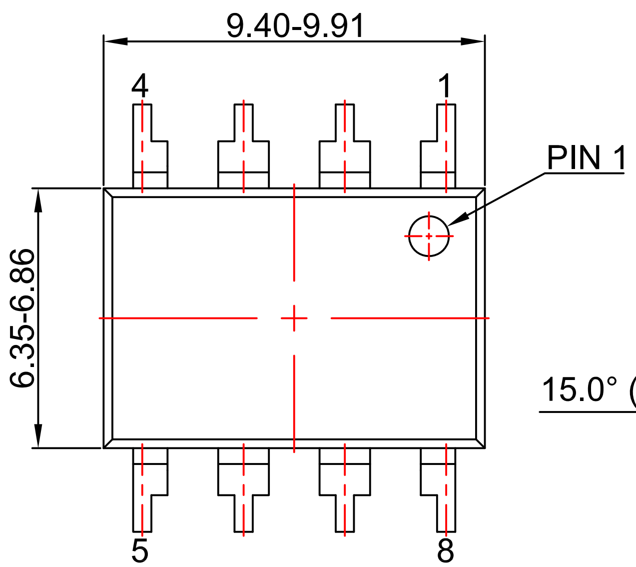

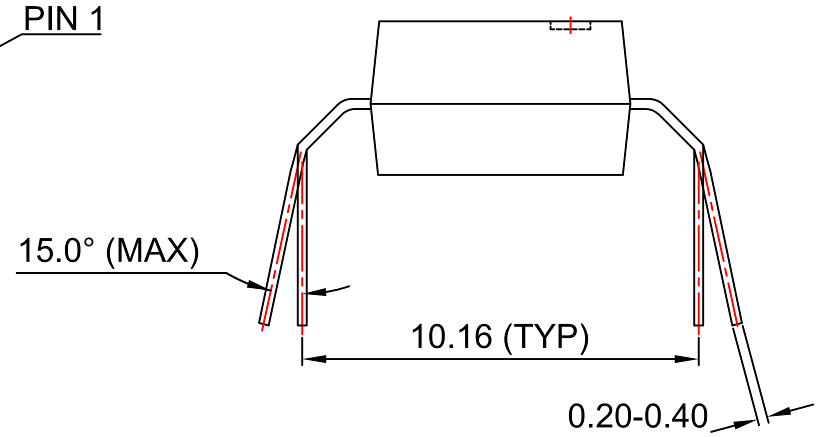

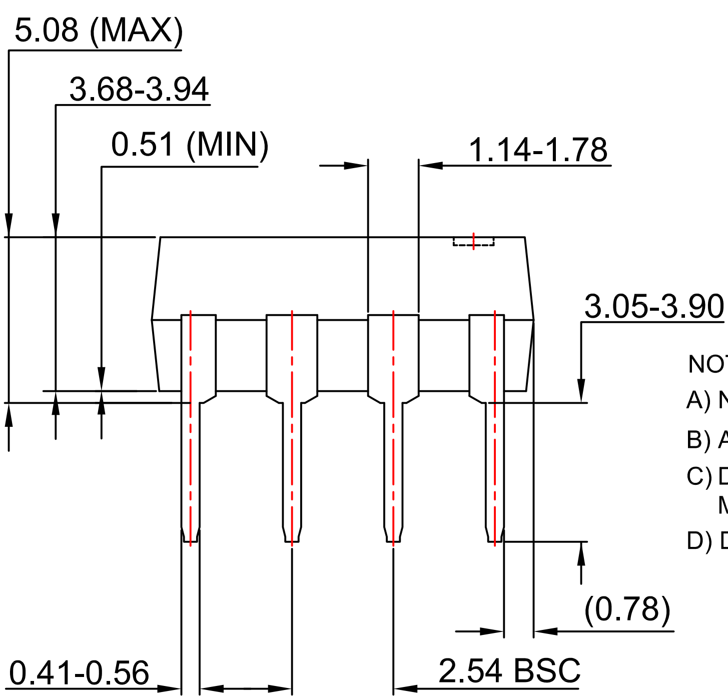

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ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- *Конкурентоспособные цены и скидки постоянным клиентам.*
- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

- *Сертификаты соответствия на поставляемую продукцию (по желанию клиента).*
- *Тестирование поставляемой продукции.*
- *Поставку компонентов, требующих военную и космическую приемку.*
- *Входной контроль качества.*
- *Наличие сертификата ISO.*

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- *Регистрацию проекта у производителя компонентов.*
- *Техническую поддержку проекта.*
- *Защиту от снятия компонента с производства.*
- *Оценку стоимости проекта по компонентам.*
- *Изготовление тестовой платы монтаж и пусконаладочные работы.*

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